



INCHES			MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.037	0.043	0.940	1.100
A1	0.000	0.006	0.000	0.150
A2	0.030	0.037	0.750	0.950
B	0.010	0.014	0.250	0.360
C	0.005	0.007	0.130	0.180
D	0.116	0.120	2.950	3.050
e	0.0256	BSC	0.65	BSC
E	0.116	0.120	2.950	3.050
H	0.188	0.198	4.780	5.030
L	0.016	0.026	0.410	0.660
L1	0.037	REF.	0.940	REF.
α	0°	6°	0°	6°
*X	0.087	0.099	2.210	2.515
*Y	0.062	0.074	1.575	1.880

* EXPOSED PAD

NOTES:

1. D&E DO NOT INCLUDE MOLD FLASH.
2. MOLD FLASH OR PROTRUSIONS NOT TO EXCEED 0.15MM (.006").
3. CONTROLLING DIMENSION: MILLIMETERS.
4. MEETS JEDEC MO-187.
5. EXPOSED PAD FLUSH WITH BOTTOM OF PACKAGE WITHIN .002".
6. MARKING IS FOR PACKAGE ORIENTATION REFERENCE ONLY.
7. COPLANARITY SHALL NOT EXCEED 0.10mm.

-DRAWING NOT TO SCALE-

 DALLAS SEMICONDUCTOR			
TITLE			
PACKAGE OUTLINE, 8L uMAX/uSOP, EXPOSED PAD			
APPROVAL	DOCUMENT CONTROL NO. 21-0107	REV. C	1/1